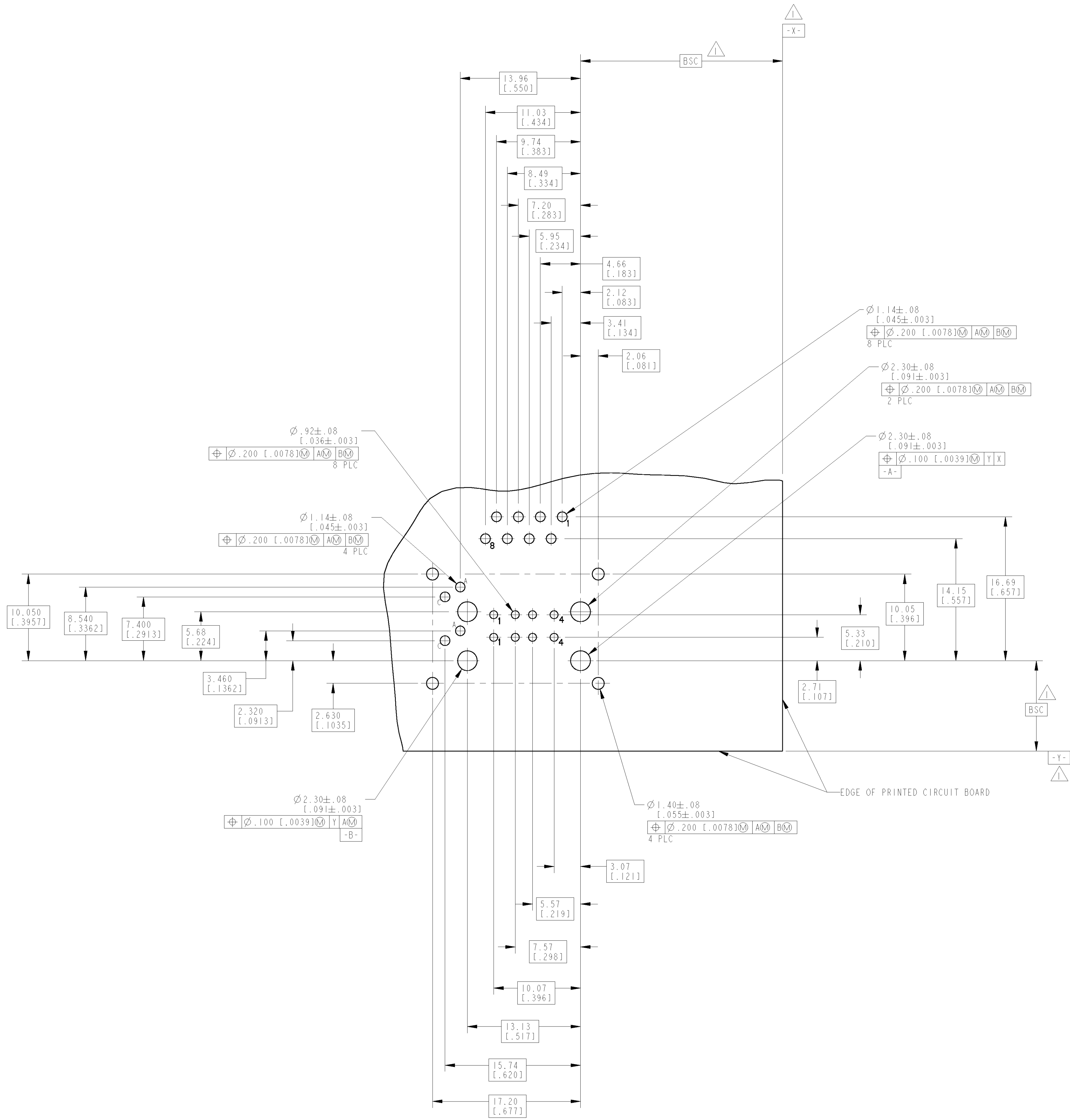


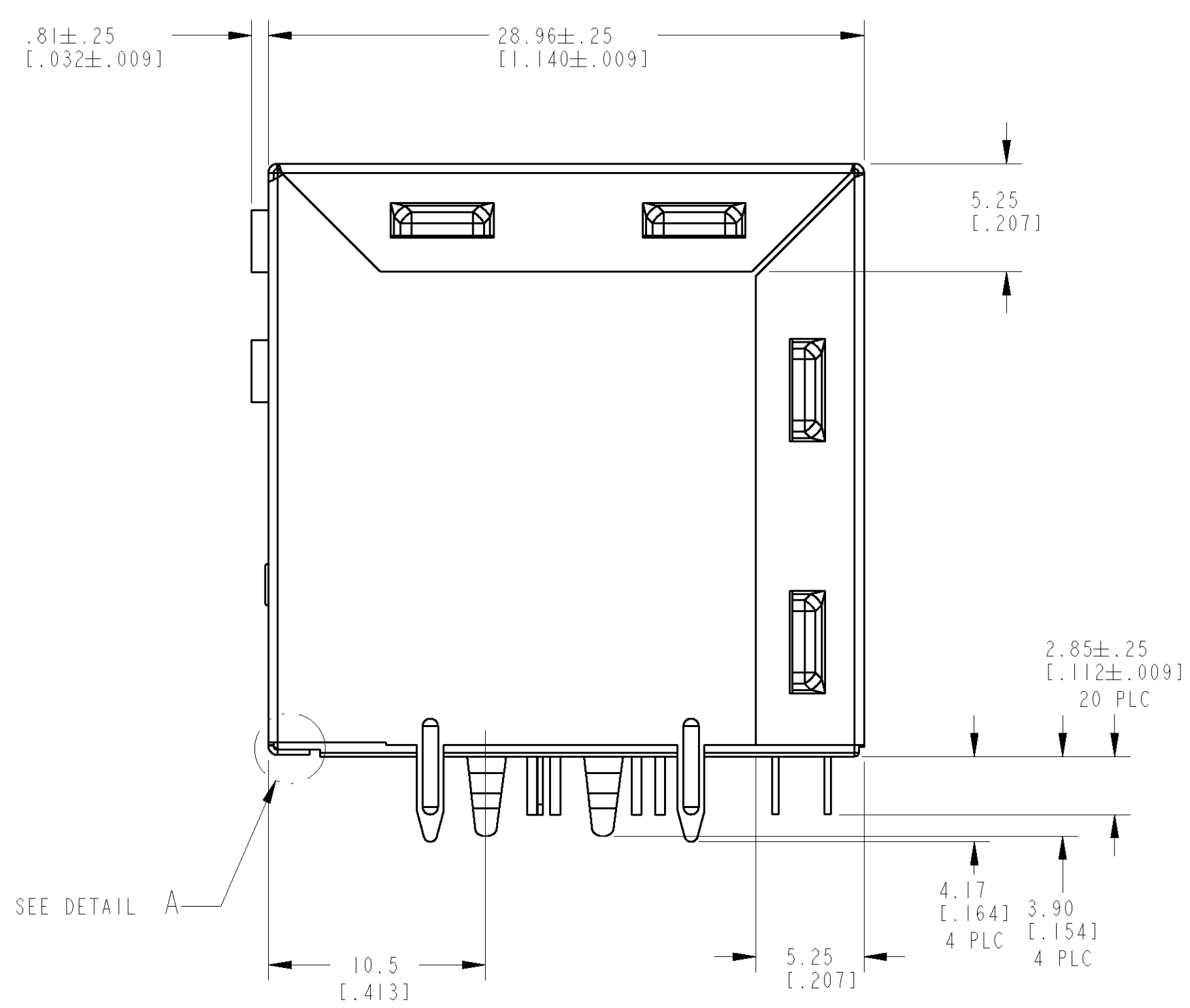
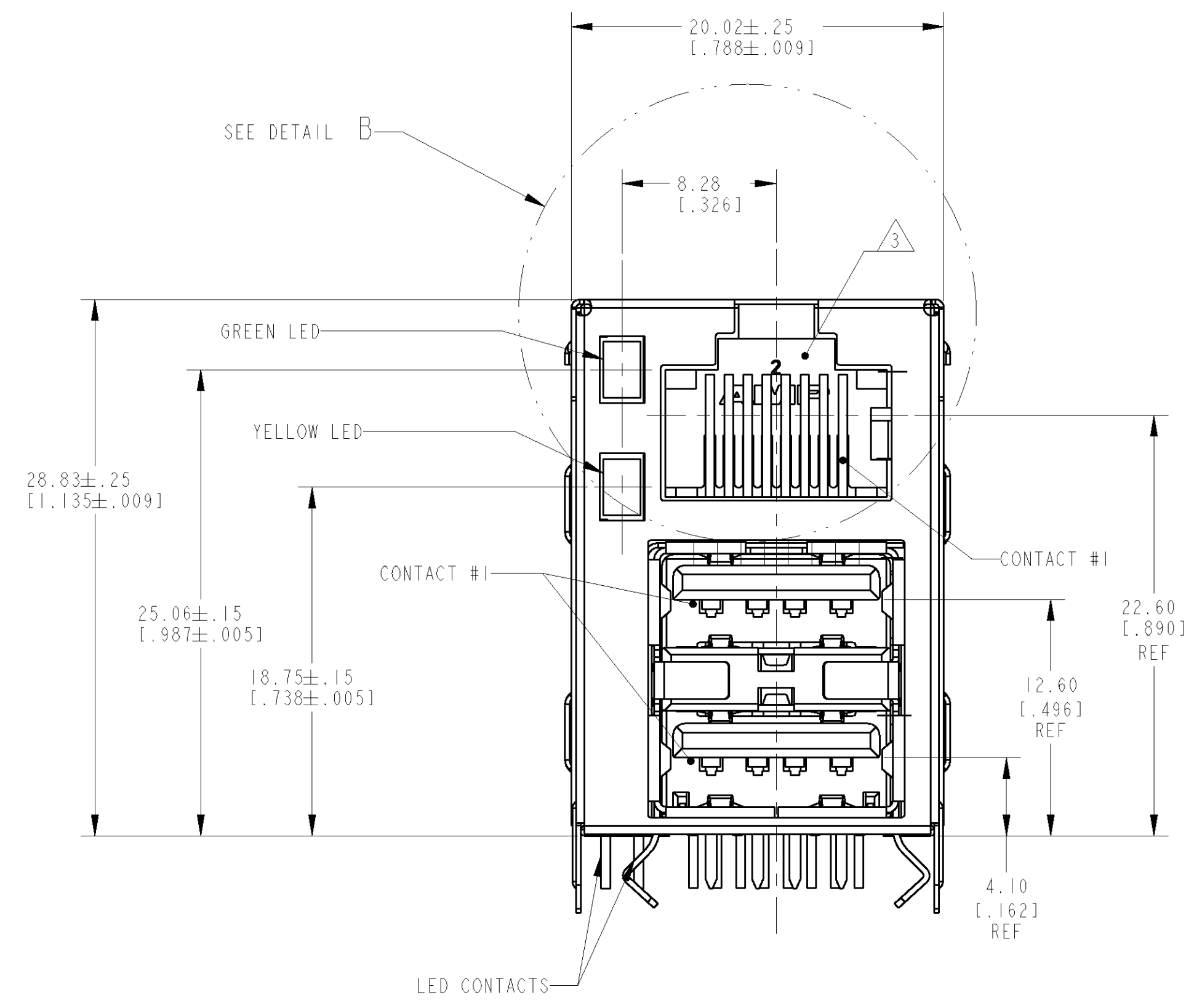
LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
-	-	SEE SHEET 1	-	-	-		



RECOMMENDED PCB LAYOUT

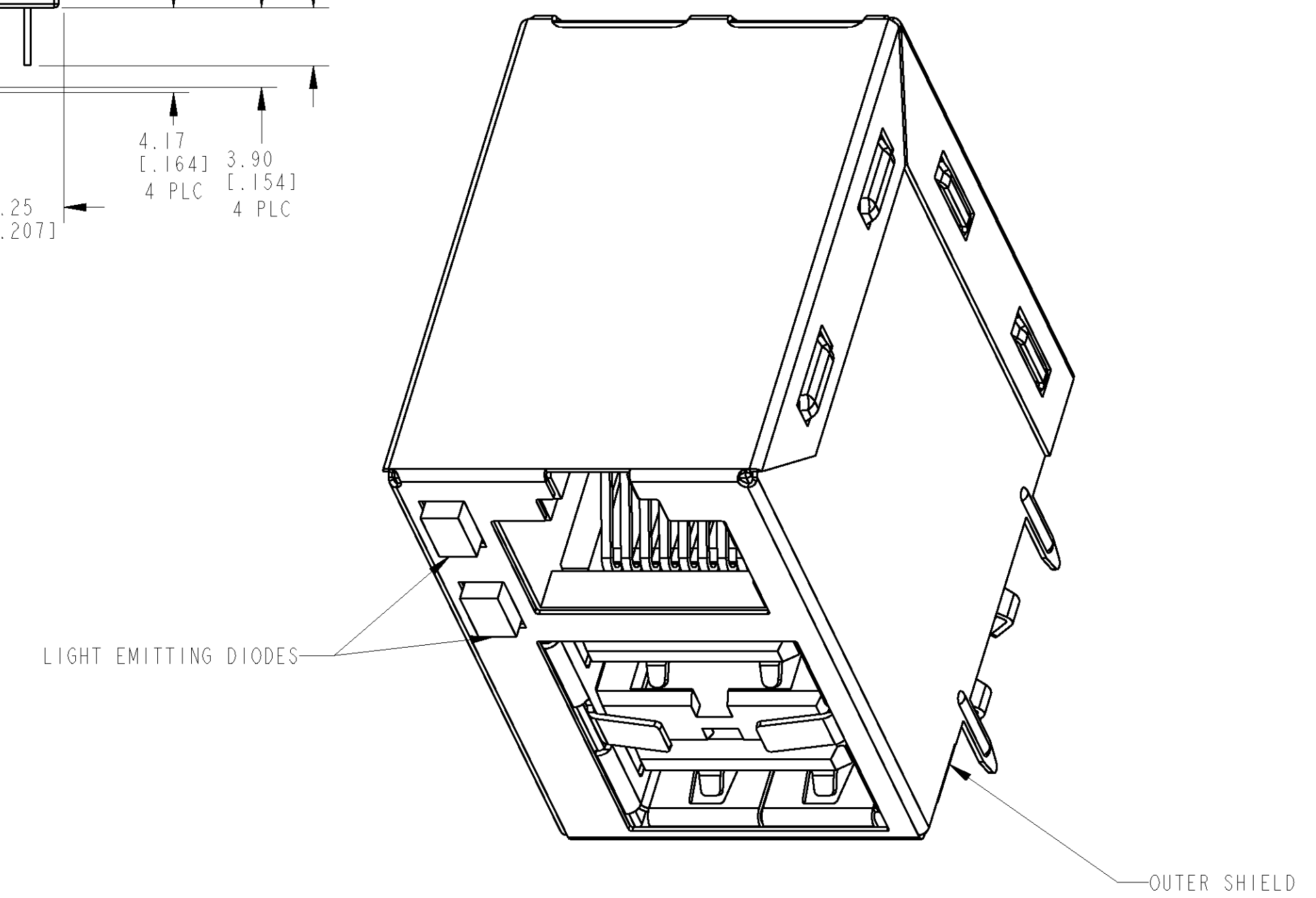
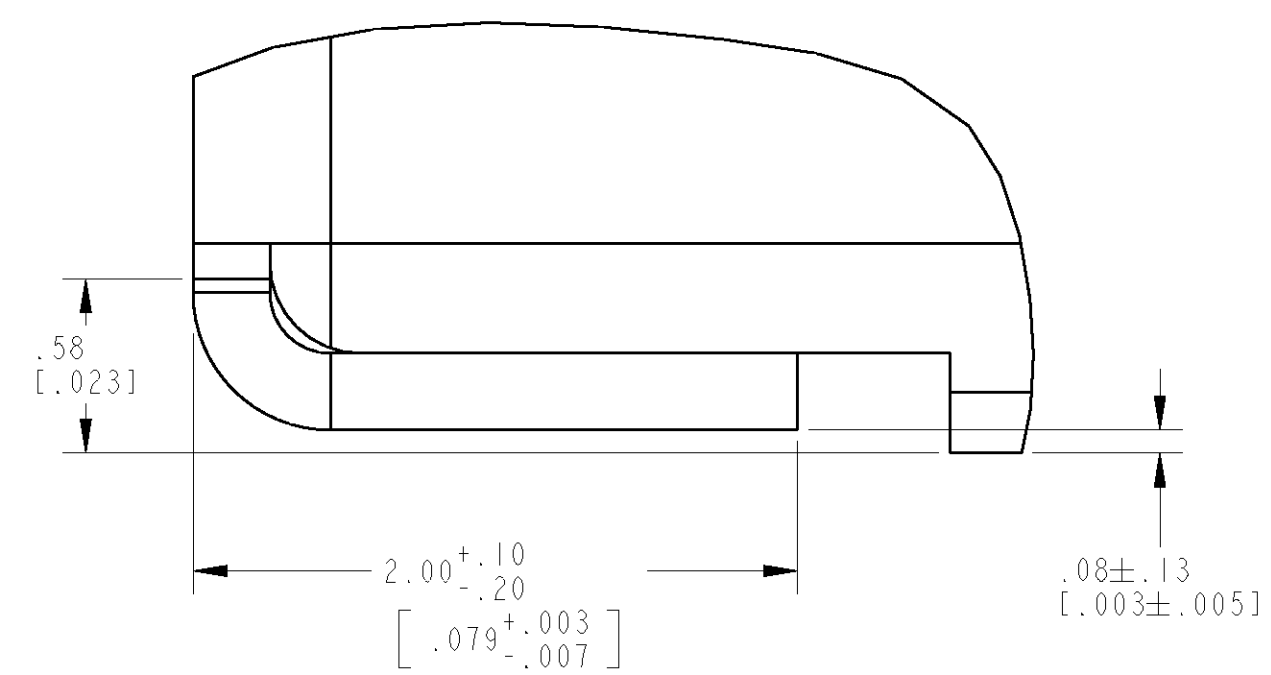
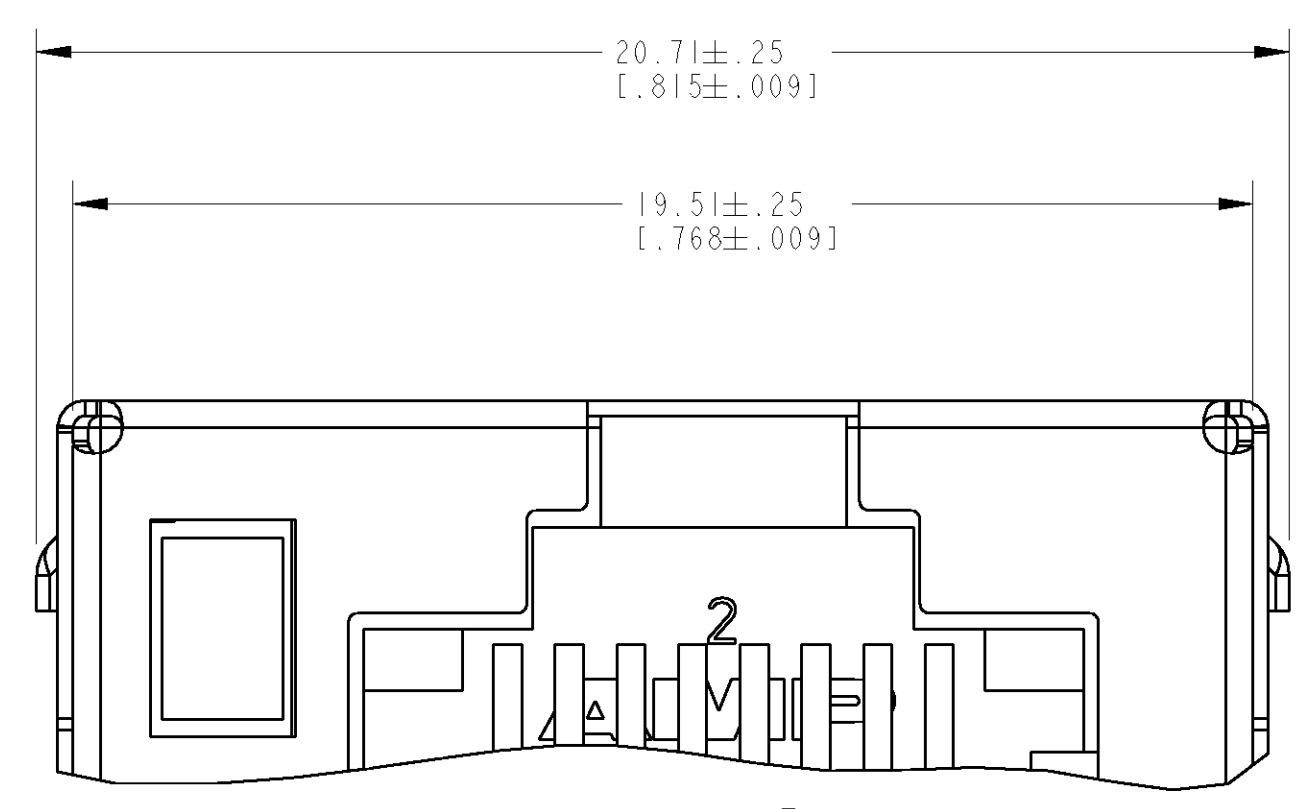
<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. IT IS THE PROPERTY OF TYCO ELECTRONICS CORPORATION. IT IS TO BE USED ONLY FOR THE SPECIFIC PROJECT AND ORGANIZATION FOR WHICH IT WAS PREPARED. IT IS NOT TO BE REPRODUCED OR DISTRIBUTED OUTSIDE OF THE COMPANY OR ORGANIZATION WITHOUT THE WRITTEN PERMISSION OF TYCO ELECTRONICS CORPORATION.</small>		DWN: J. GERACE/L. A. MAYER CDR: J. WESTMAN APVD: S. FLICKINGER	DATE: 14APR2005 DATE: 14APR2005	tyco Electronics	AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13(.005) 3 PLC ± 4 PLC ± ANGLES ±1°	NAME: S. FLICKINGER PRODUCT SPEC: APPLICATION SPEC: WEIGHT:	SIZE: A CAGE CODE: 00779 DRAWING NO: C=6116640	RESTRICTED TO:	SCALE: 4:1 SHEET: 2 OF 2 REV: A
MATERIAL: SEE NOTE 4 FINISH: SEE NOTE 4		CUSTOMER DRAWING			

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DRN	APVD
AA	22	A	ECOS11-0204-04	14APR2005	LAM SF



- 1 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 2 RECOMMENDED PC BOARD THICKNESS IS 2.36 [1.093].
- 3 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F

4. MATERIAL:
 HOUSING: PLASTIC HOUSINGS: UL94V-0/5V THERMOPLASTIC, SEE TABLE FOR COLOR.
 TERMINAL: USB: 0.251 ± 0.013 THICK PHOSPHOR BRONZE PLATED WITH 1.27 μm NICKEL. IN LOCALIZED GOLD PLATE AREA 0.076 μm MIN GOLD OVER 0.76 μm MIN PALLADIUM-NICKEL IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8 μm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 RJ45: 0.318 THICK PHOSPHOR BRONZE PLATED WITH 1.27 μm MIN THICK NICKEL. IN LOCALIZED GOLD PLATE AREA 1.27 μm MIN THICK GOLD IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8 μm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 LED: 0.5 DIAMETER CARBON STEEL LEADS PREPLATED WITH 8.89 μm THICK Sn/Cu, OVER 2.03 μm THICK Ag, OVER 1.02 μm THICK Cu, OVER 3.56 μm THICK Ni, OVER 1.02 μm Cu UNDERPLATE
 SHIELD: OUTER: 0.254 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2 μm TO 3.8 μm THICK.
 INNER: 0.318 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2 μm TO 3.8 μm THICK.
 USB: 0.318 THICK PHOSPHOR-BRONZE PREPLATED WITH 5.1 μm MIN TIN



WITH LEADS	6116640-1
DESCRIPTION	PART NO.

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DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13 [0.005] 3 PLC ± 4 PLC ± ANGLES ±1°	PRODUCT SPEC APPLICATION SPEC	ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE	RESTRICTED TO
MATERIAL: SEE NOTE 4	FINISH: SEE NOTE 4	WEIGHT: - CUSTOMER DRAWING	SIZE: A 00779 C=6116640 SCALE: 4:1	SHEET 1 OF 2 REV A